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(12) **United States Design Patent** (10) **Patent No.:** **US D902,163 S**
Ice et al. (45) **Date of Patent:** **** Nov. 17, 2020**

- (54) **SURFACE-MOUNTABLE HEAT SINK**
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- (73) Assignee: **Osram Sylvania Inc.**, Wilmington, MA (US)

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(**) Term: **15 Years**

(21) Appl. No.: **29/709,510**

(22) Filed: **Oct. 15, 2019**

Related U.S. Application Data

(60) Division of application No. 29/627,131, filed on Nov. 22, 2017, now Pat. No. Des. 873,223, which is a continuation-in-part of application No. 29/605,144, filed on May 24, 2017, now Pat. No. Des. 878,312.

(51) **LOC (12) Cl.** **13-03**

(52) **U.S. Cl.**
USPC **D13/179**; D8/395

(58) **Field of Classification Search**
USPC D13/179; D26/138, 141, 152, 142, 63;
D8/394, 354, 395
CPC . H05K 7/20254; H05K 7/20418; F28F 3/022;
F28F 3/04; F28F 21/065; H01L 23/367;
H01L 23/3672; H01L 23/3677; H01L
23/36; H01L 23/4006; G02B 1/111; A61B
17/50; A61M 37/0015
See application file for complete search history.

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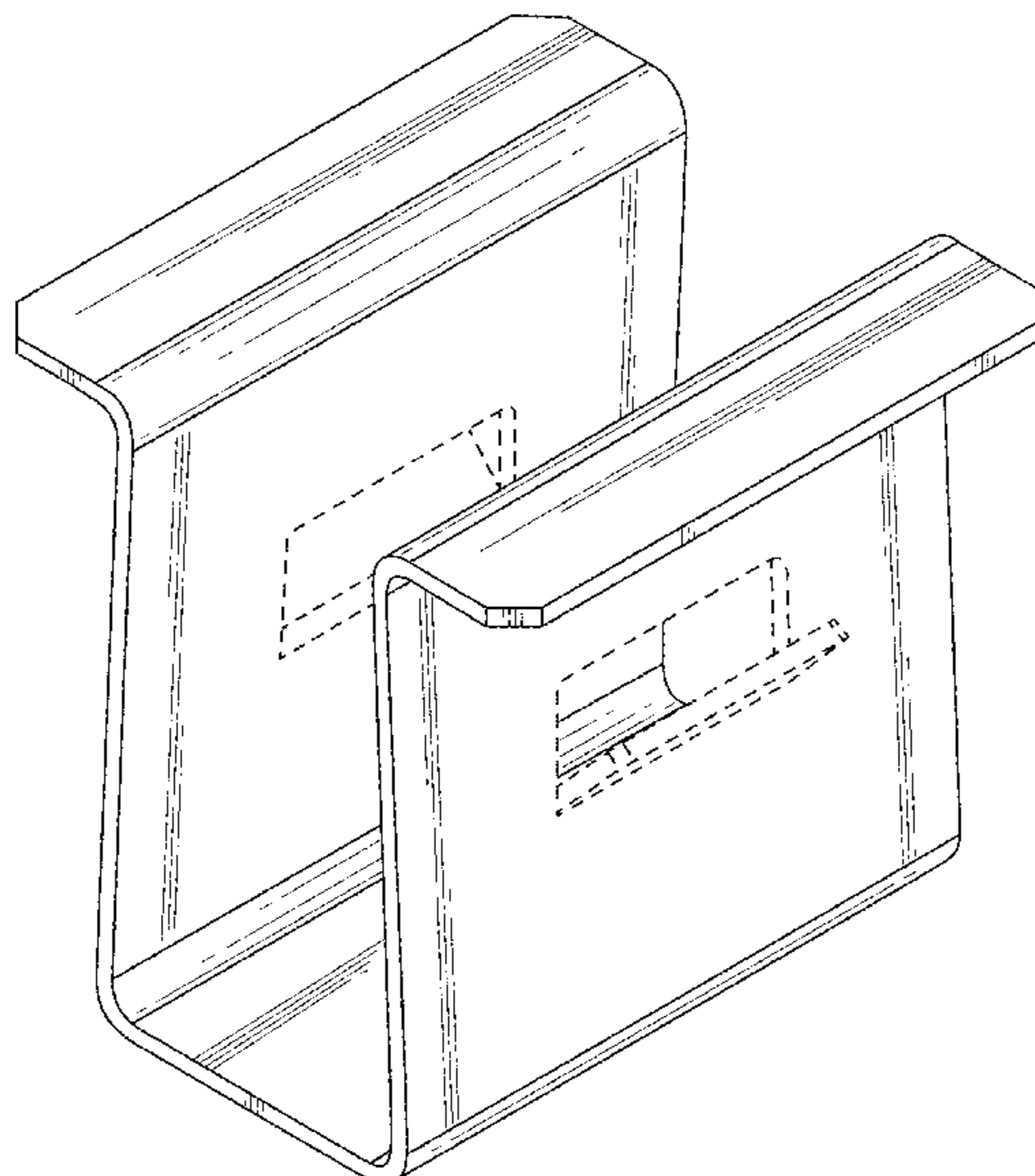
(57) **CLAIM**

The ornamental design for a surface-mountable heat sink, as shown and described.

DESCRIPTION

FIG. 1 is a top view of the design for a surface-mountable heat sink;
FIG. 2 is a front elevational view thereof, the opposite rear view being the same;
FIG. 3 is a bottom view thereof;
FIG. 4 is a side elevational view thereof, the opposite side view being the same;
FIG. 5 is a front, top perspective view thereof; and,
FIG. 6 is a bottom perspective view thereof.
The broken-line disclosure in the views is understood to represent portions of the article in which the claimed design is embodied, but which form no part of the claimed design.

1 Claim, 6 Drawing Sheets



(56)

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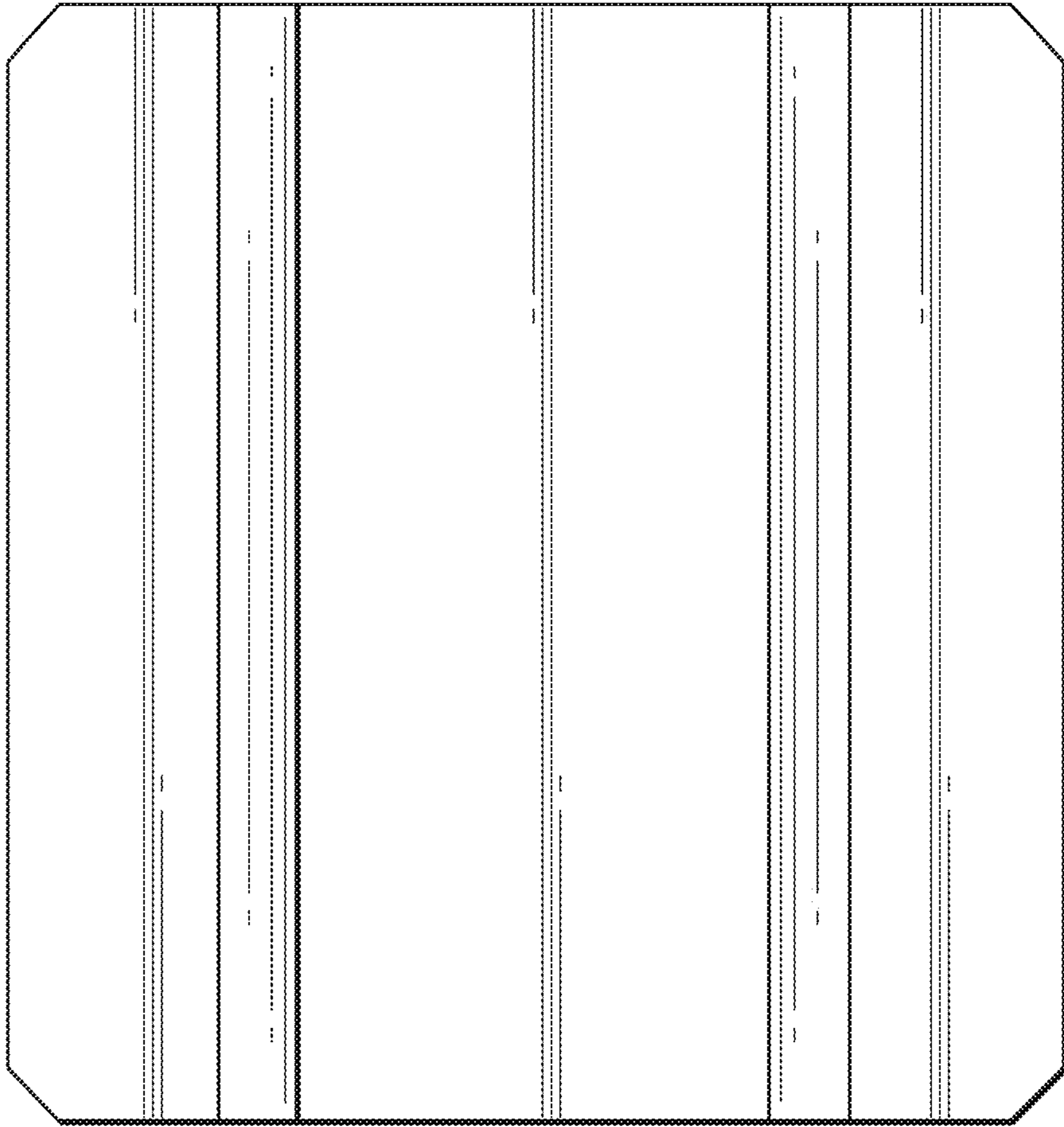


FIG. 1

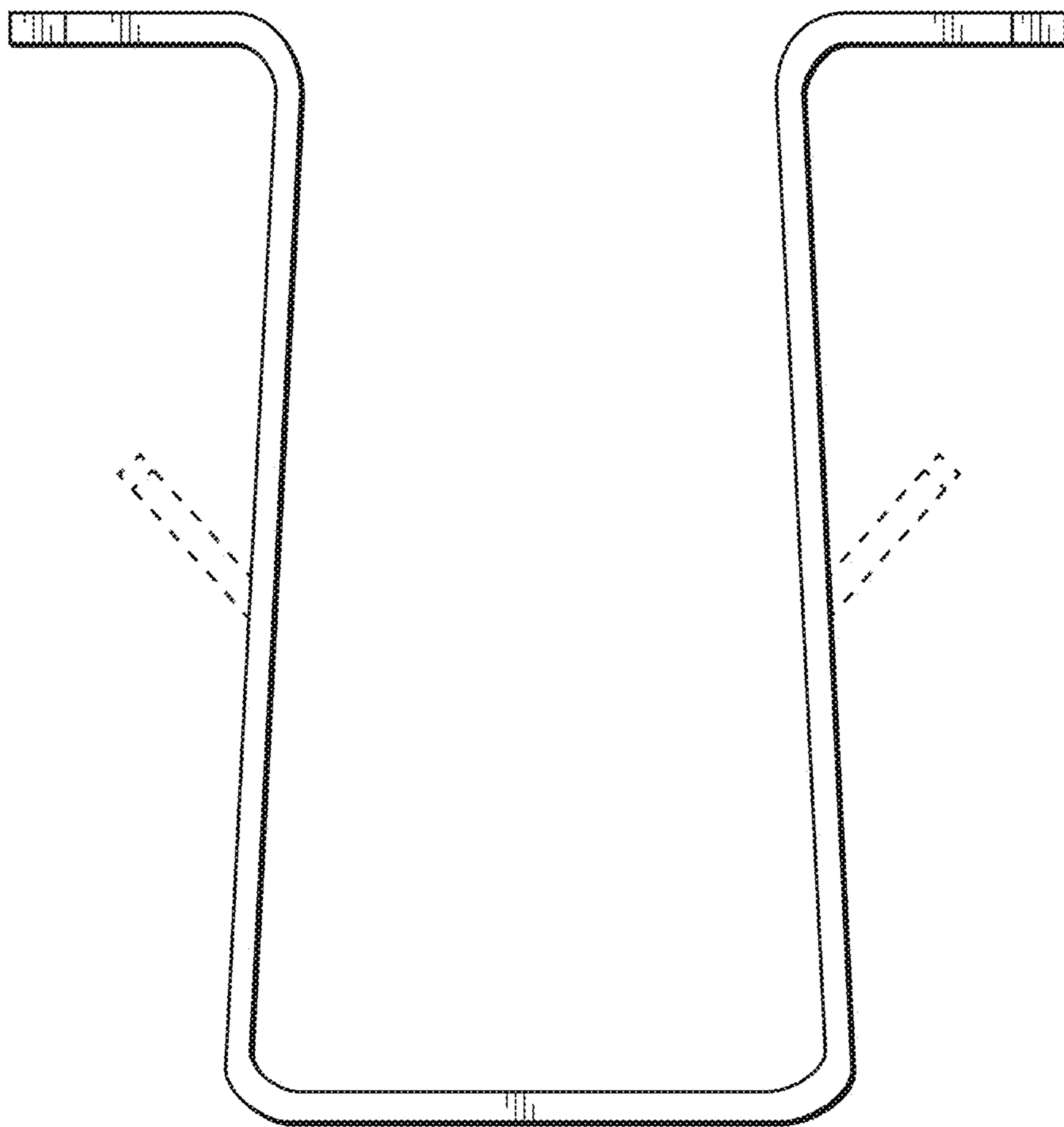


FIG. 2

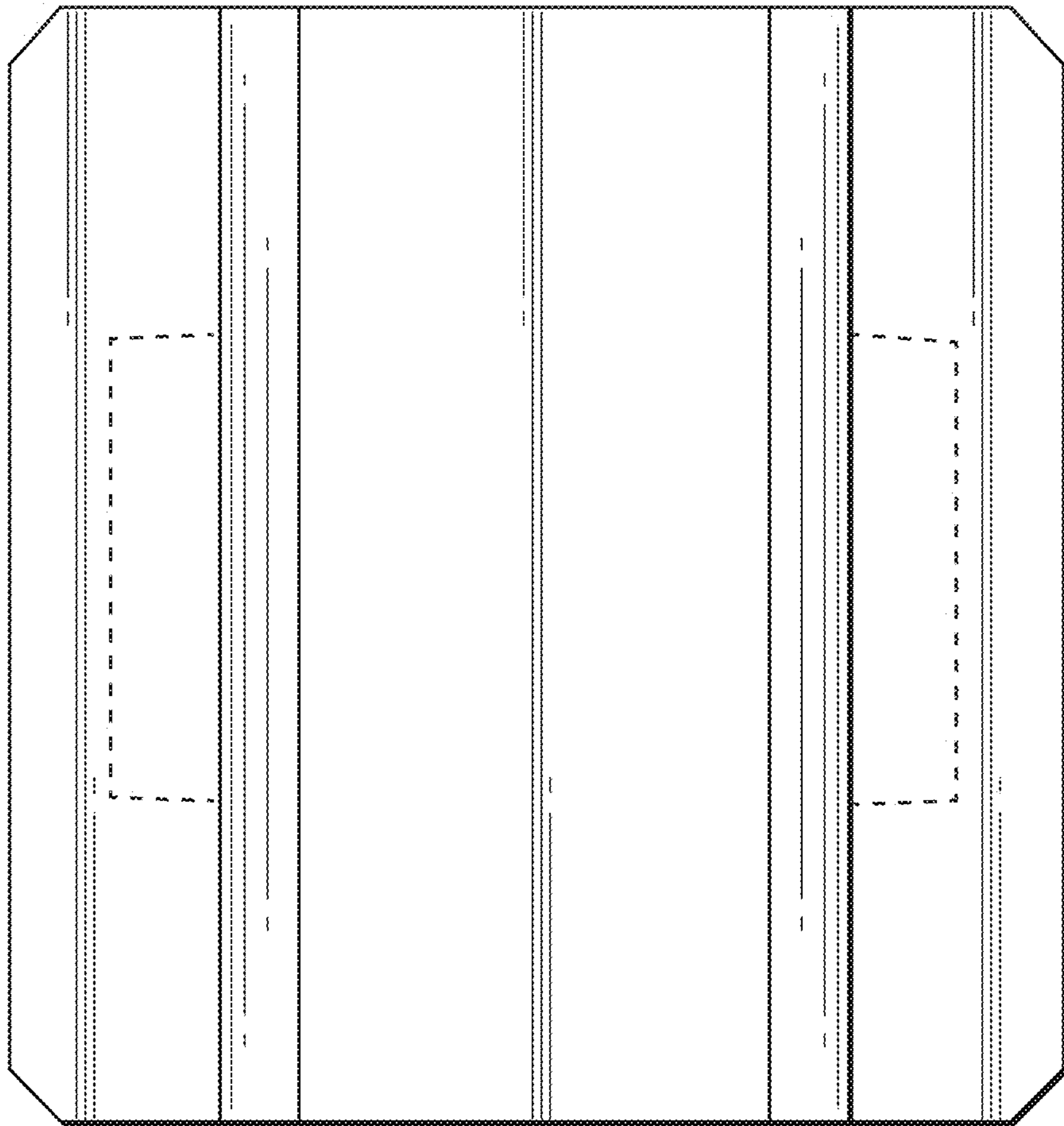


FIG. 3

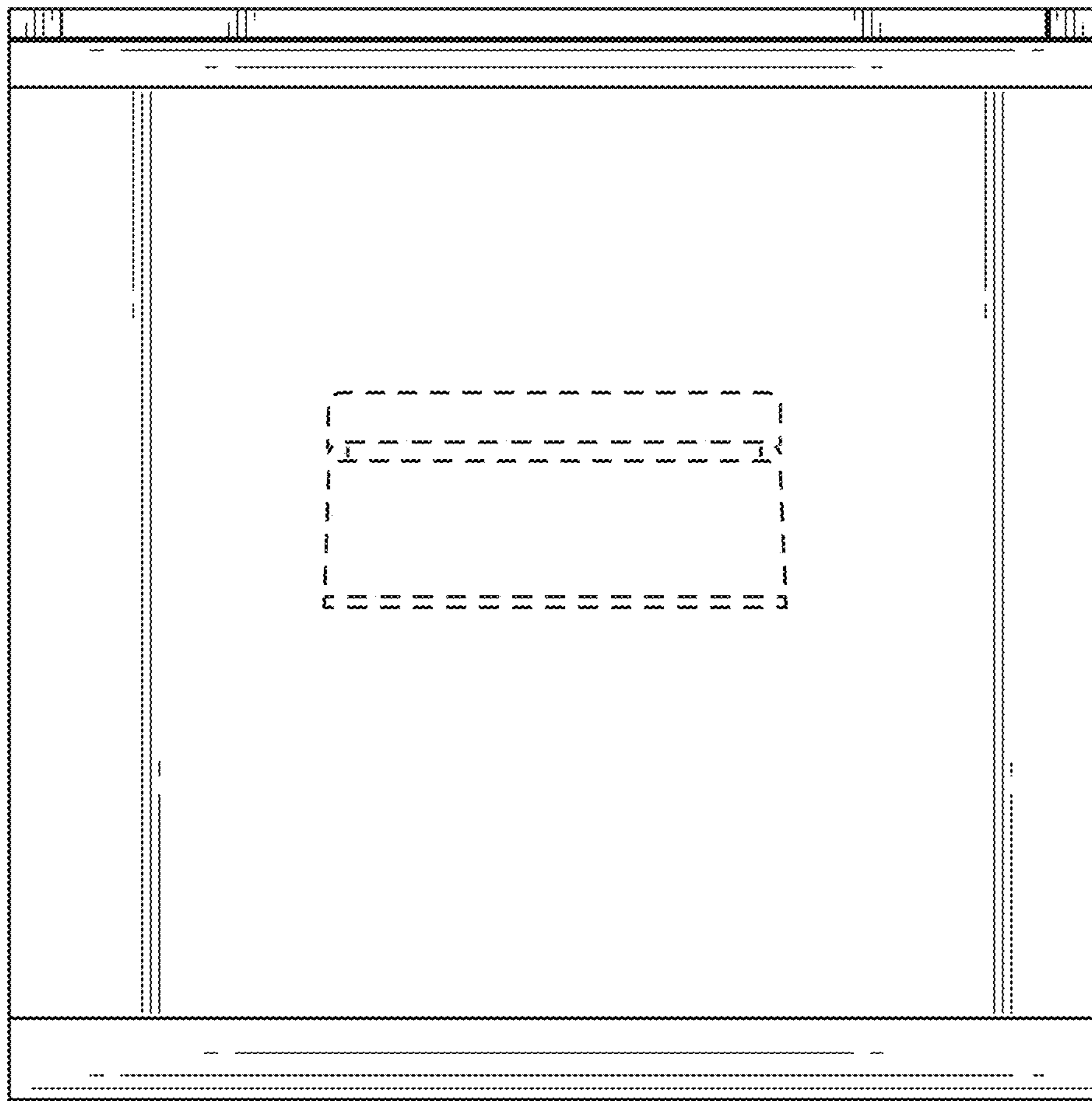


FIG. 4

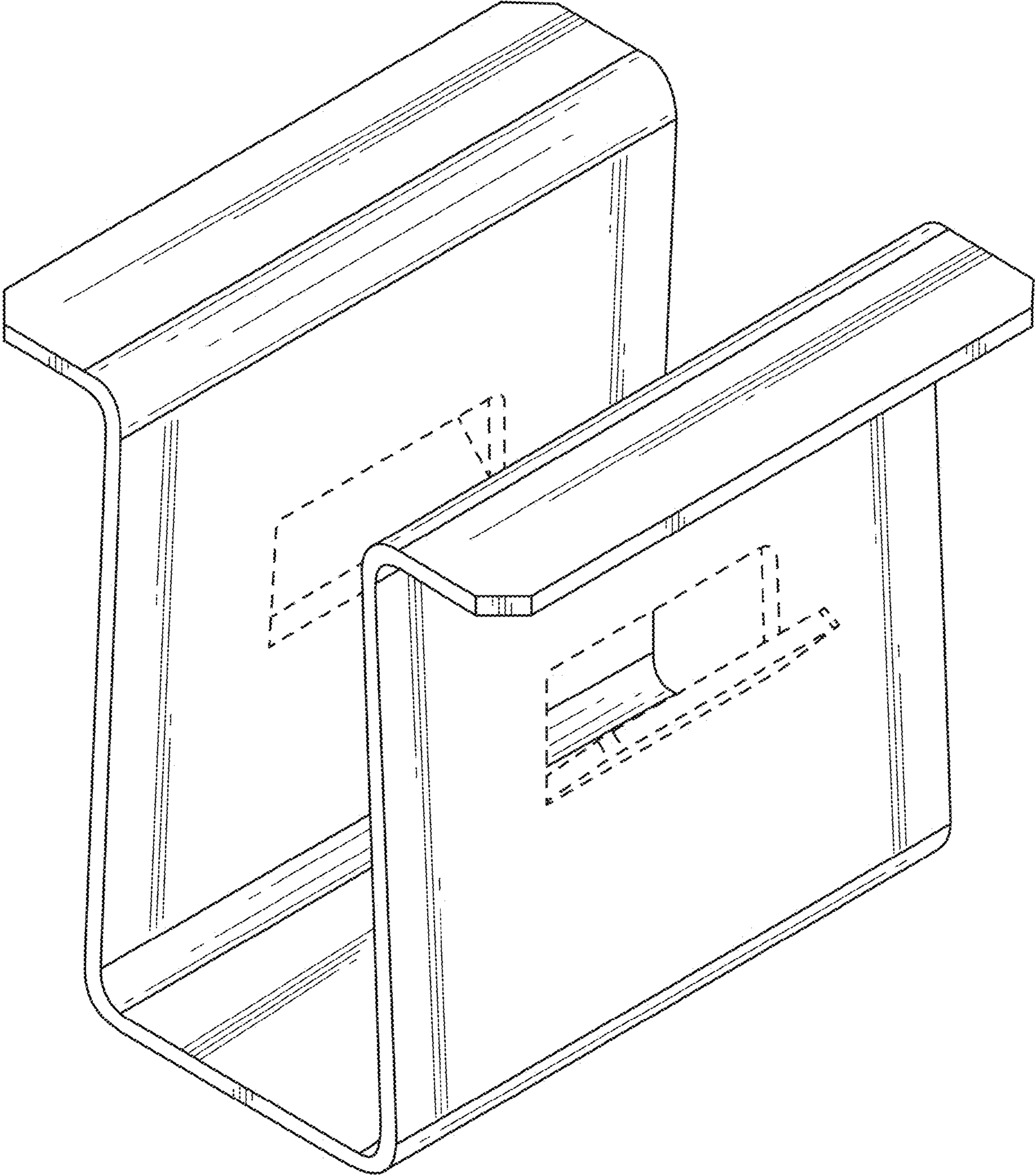


FIG. 5

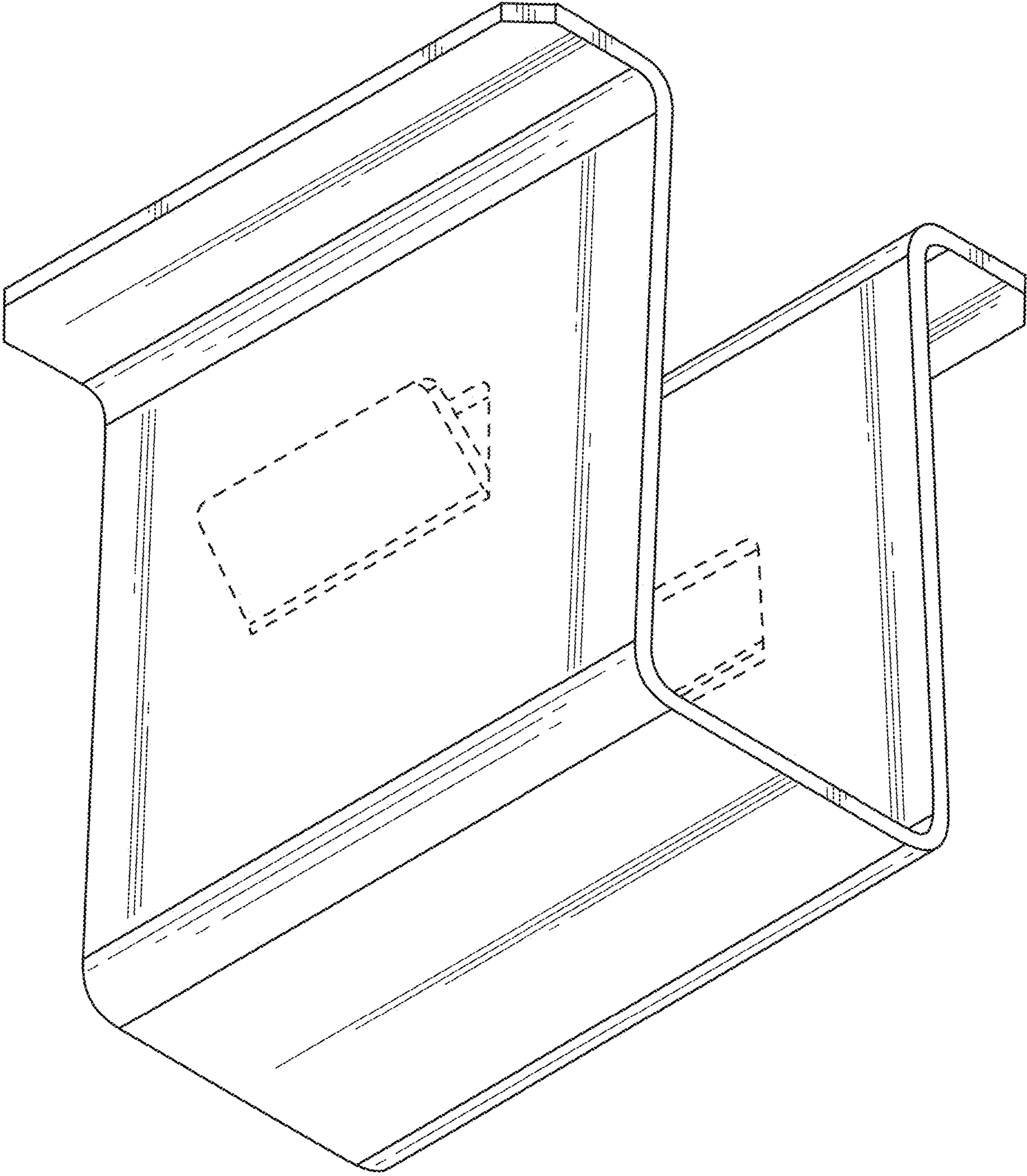


FIG. 6